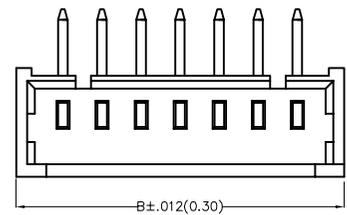
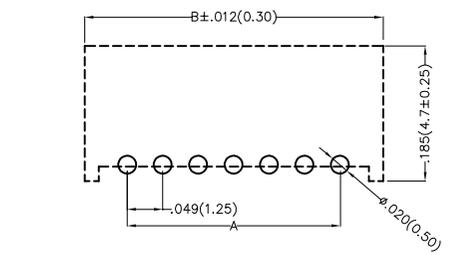
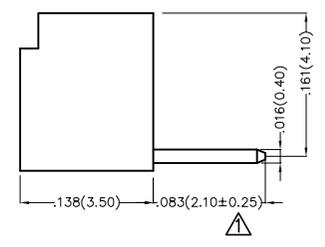
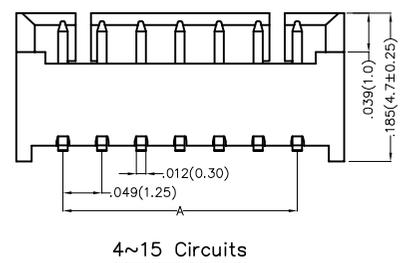
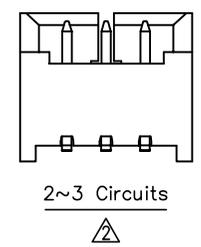


1 2 3 4 5 6 7 8

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	Tolerances change	25/MAY/20	KATE	CHERRY
2	△	Add 2-3 Circuits view	27/DEC/23	KATE	LEO
3	△	Correct the Color-Resin	01/APR/26	MATT	LEO



Electrical
 Current Rating: 1.0A AC(rms)/DC
 Voltage Rating: 125V AC(rms)/DC
 Contact Resistance: 20 mΩ Max
 Insulation Resistance: 100 MΩ MIN
 Withstanding Voltage: 250V AC r.m.s
 Temperature Range-Operating: -40°C ~+85°C
Material and Plating
 Housing: PA46(UL 94V-0)
 Contact Pin: Phosphor bronze
 Mates With: FHG12502 Series.



Recommended P.C.Board Layout

Ordering Information

FWF 125 07 - S XX B X 4 W5 B
 1 2 3 4 5 6 7 8 9 10

1 Category FWF-Wafer	2 Series Number 125-Pitch1.25mm	3 Distinction No. 07	4 Row Option S-Single Row	5 Circuits XX	6 Entry Angle B-90° Angle
7 Plating 2-Tin Plated	8 Material-Resin 4-PA46	9 Color-Resin W5-Natural △	10 Packaging B-PE Bag		

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 8/JUL/13	PART NO. FWF12507-SXXBX4W5B	ITEM NO. FWF12507	 Building Technology Cornerstone	
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.X±.008(0.20) X.XX±.006(0.15) X.XXX±.004(0.10)	X:±5' .X:±2' .XX:±1' .XXX:±0.5'	CHECKED BY JACOB	DATE 8/JUL/13	TITLE Wire to Board (Wafer) Pitch 1.25mm 90° Angle (DIP)		REV 3
SCALE 5:1	SIZE A4	DRAWN BY CHERRY		DATE 8/JUL/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

1 2 3 4 5 6 7 8

1 2 3 4 5 6 7 8

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

A

B

C

D

E

F

A

B

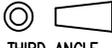
C

D

E

F

Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
2	FWF12507-S02B24W5B	.049(1.25)	.167(4.25)
3	FWF12507-S03B24W5B	.098(2.50)	.217(5.50)
4	FWF12507-S04B24W5B	.147(3.75)	.266(6.75)
5	FWF12507-S05B24W5B	.197(5.00)	.315(8.00)
6	FWF12507-S06B24W5B	.246(6.25)	.364(9.25)
7	FWF12507-S07B24W5B	.295(7.50)	.413(10.50)
8	FWF12507-S08B24W5B	.344(8.75)	.463(11.75)
9	FWF12507-S09B24W5B	.394(10.00)	.512(13.00)
10	FWF12507-S10B24W5B	.443(11.25)	.561(14.25)
11	FWF12507-S11B24W5B	.492(12.50)	.610(15.50)
12	FWF12507-S12B24W5B	.541(13.75)	.659(16.75)
13	FWF12507-S13B24W5B	.591(15.00)	.709(18.00)
14	FWF12507-S14B24W5B	.640(16.25)	.757(19.25)
15	FWF12507-S15B24W5B	.689(17.50)	.807(20.50)

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Building Technology Cornerstone
	X.±.012(0.30)	X'.±5'	FRANK	8/JUL/13	FWF12507-SXXBX4W5B	FWF12507	
	X.X±.008(0.20)	.X'±2'	CHECKED BY	DATE	TITLE		
	X.XX±.006(0.15)	.XX'±1'	JACOB	8/JUL/13	Wire to Board (Wafer) Pitch 1.25mm 90° Angle (DIP)		
SCALE	SIZE	X.XXX±.004(0.10)	.XXX'±0.5'	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
5:1	A4			CHERRY	8/JUL/13	REV 3	SHEET NO. 2/2

1 2 3 4 5 6 7 8